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COMPOSITE FIELD EFFECT TRANSISTOR

CROSS-REFERENCE TO RELATED APPLICATIONS

This application claims the benefit of U.S. Provisional Application No. 60/663,315 filed Mar. 18, 2005.

BACKGROUND OF THE INVENTION

Depletion mode junction field effect transistors (JFETs) are efficient semiconductor structures, especially for high-voltage switching applications. However, depletion mode JFETs require a negative gate-to-source potential to turn off. Accordingly, when a system incorporating a JFET is first 15 turned on, the depletion mode JFET is also on, causing undesirable high current to flow in most applications.

An enhancement mode metal-oxide-semiconductor field effect transistor (MOSFET), on the other hand, requires a positive voltage to turn on. Therefore, the MOSFET, being 20 a normally off device, does not typically exhibit high current flows in most applications upon start-up. However, MOSFETs are generally not normally the most cost-efficient devices for high voltage (>100V) applications.

Accordingly, there remains a need for semiconductor 25 device having C) improved high-voltage switching characteristics in combination with low current flow characteristics at start-up and no requirement for negative gate bias.

SUMMARY OF THE INVENTION

Embodiments of the present invention provide a composite field effect transistor that includes a zener diode, a junction field effect transistor and a metal-oxide-semiconductor field effect transistor. A gate of the junction field 35 effect transistor is coupled to an anode of the zener diode. A cathode of the zener diode is coupled to a gate of the metal-oxide-semiconductor field effect transistor. A drain of the metal-oxide-semiconductor field effect transistor is coupled to a source of the junction field effect transistor. In 40 one implementation, the junction field effect transistor is a depletion mode device and the metal-oxide-semiconductor field effect transistor is an n-channel enhancement mode device.

BRIEF DESCRIPTION OF THE DRAWINGS

Embodiments of the present invention are illustrated by way of example and not by way of limitation, in the figures of the accompanying drawings and in which like reference 50 numerals refer to similar elements and in which:

FIG. 1 shows a diagram of a composite field effect transistor (FET), in accordance with one embodiment of the invention.

FIG. 2 shows a diagram of a composite FET, in accor- 55 dance with another embodiment of the invention.

DETAILED DESCRIPTION OF THE INVENTION

Reference will now be made in detail to the embodiments of the invention, examples of which are illustrated in the accompanying drawings. While the invention will be described in conjunction with these embodiments, it will be understood that they are not intended to limit the invention 65 to these embodiments. On the contrary, the invention is intended to cover alternatives, modifications and equiva-

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lents, which may be included within the scope of the invention as defined by the appended claims. Furthermore, in the following detailed description of the present invention, numerous specific details are set forth in order to provide a thorough understanding of the present invention. However, it is understood that the present invention may be practiced without these specific details. In other instances, well-known methods, procedures, components, and circuits have not been described in detail as not to unnecessarily obscure aspects of the present invention.

FIG. 1 shows a diagram of a composite field effect transistor (FET) 100 having a gate, drain and source, in accordance with one embodiment of the invention. The composite FET 100 includes a depletion mode junction field effect transistor (JFET) 110 (Q1), an enhancement mode N-channel metal-oxide-semiconductor field effect transistor (MOSFET) 120 (Q2) and a zener diode 130 (CR1). The drain of the JFET 110 is coupled to the drain of the composite FET 100. The source of the JFET 110 is coupled to the drain of the MOSFET 120. The source of the MOS-FET 120 is coupled to the source of the composite FET 100. The anode of the zener diode 130 is coupled to the gate of the JFET 110 and the cathode of the zener diode 130 is coupled to the gate of the MOSFET 120. The gate of the MOSFET 120 is also coupled to the gate of the composite FET 100.

When the gate-to-source potential of the composite FET 100 is less than the threshold voltage $(V_{T(Q2)})$ of the MOSFET 120, the MOSFET 120 is turned off and blocks current from flowing between the source and drain of the composite FET 100. When the gate-to-source potential of the composite FET 100 is greater than the threshold voltage of the MOSFET 120 and less than the breakdown voltage of the zener diode 130, the MOSFET 120 will turn on pulling the source of the JFET 100 down. However, the zener diode 130 blocks the potential at the gate of the JFET 110 and therefore the JFET 110 remains off.

When the gate-to-source potential of the composite FET 100 reaches the threshold voltage of the JFET 110 plus the breakdown voltage of the zener diode 130 ($V_{GS(Q1)}+V_{Z(CR1)}$), both the JFET 110 and MOSFET 120 are turned on and current is conducted between the source and drain of the composite FET 100. In addition, when the gate-to-source potential of the composite FET 100 reaches the threshold voltage of the JFET 110 plus the breakdown voltage of the zener diode 130 ($V_{GS(Q1)}+V_{Z(CR1)}$), current-flowing through the zener diode 120 acts to inject minority carriers into the JFET 110, thereby improving its conductivity of the composite FET 100 especially at high drain currents.

When the gate-to-source potential of the composite FET 100 pulls low, the zener diode 130 conducts in its forward direction and simultaneously pulls the gate potential of the JFET 110 negative while the gate potential of MOSFET 120 is being pulled negative. As a result, the MOSFET 120 begins to turn off. As MOSFET 120 turns off, its drain potential rises, causing the gate-to-source voltage of the JFET 110 to be negative, which in turn causes the JFET 110 to turn off completely, blocking current from flowing between the source and drain of the composite FET 100.

FIG. 2, shows a diagram of a composite FET 200, in accordance with another embodiment of the invention. The composite FET 200 is illustrated coupled to a high voltage source 220 and an external drive circuit 220. The high voltage source 210 is coupled to the drain of the composite FET 200. The external drive circuit 220 is coupled to the gate of the composite FET 200.